# **4AK23**

## Silicon N-Channel Power MOS FET Array

# **HITACHI**

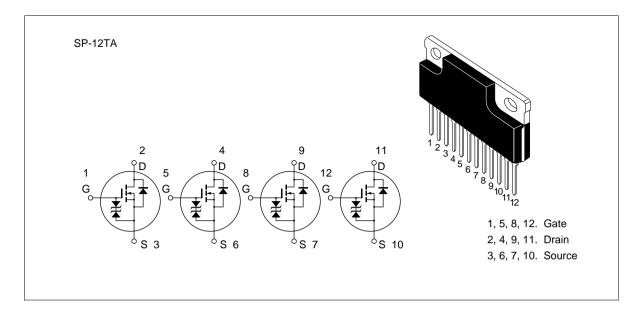
### **Application**

High speed power switching

#### **Features**

- Low on-resistance  $R_{DS(on)}$  0.25 ,  $V_{GS}$  = 10 V,  $I_D$  = 2.5 A
- Low drive current
- High speed switching
- High density mounting
- Suitable for H-bridged motor driver

### Outline





## 4AK23

### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

| Item                                      | Symbol                   | Ratings     | Unit |
|---|--------------------------|-------------|------|
| Drain to source voltage                   | $V_{	t DSS}$             | 100         | V    |
| Gate to source voltage                    | V <sub>GSS</sub>         | ±20         | V    |
| Drain current                             | I <sub>D</sub>           | 5           | A    |
| Drain peak current                        | I <sub>D(pulse)</sub> *1 | 20          | А    |
| Body to drain diode reverse drain current | I <sub>DR</sub>          | 5           | A    |
| Channel dissipation                       | Pch (Tc = 25°C)*2        | 32          | W    |
| Channel dissipation                       | Pch*2                    | 4           | W    |
| Channel temperature                       | Tch                      | 150         | °C   |
| Storage temperature                       | Tstg                     | -55 to +150 | °C   |

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

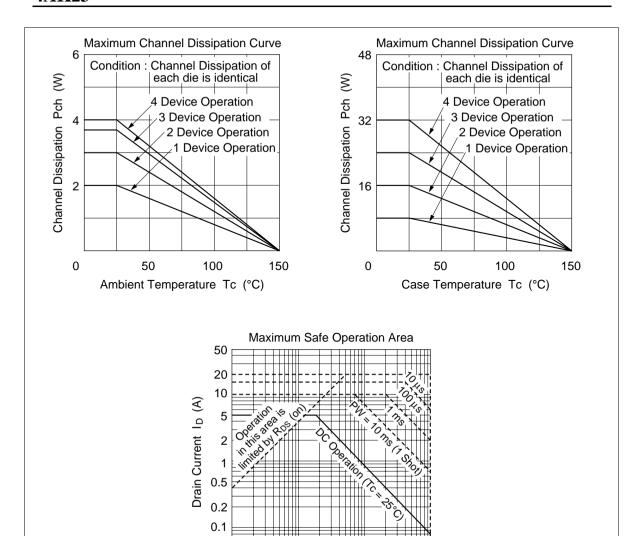
2. 4 Devices operation

### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

| Item                                       | Symbol              | Min | Тур  | Max  | Unit | Test conditions   |
|--|---------------------|-----|------|------|------|---|
| Drain to source breakdown voltage          | $V_{(BR)DSS}$       | 100 | _    | _    | V    | $I_D = 10 \text{ mA}, V_{GS} = 0$                                 |
| Gate to source breakdown voltage           | $V_{(BR)GSS}$       | ±20 | _    | _    | V    | $I_G = \pm 100 \ \mu A, \ V_{DS} = 0$                             |
| Gate to source leak current                | I <sub>GSS</sub>    | _   | _    | ±10  | μΑ   | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$                           |
| Zero gate voltage drain current            | I <sub>DSS</sub>    | _   | _    | 250  | μΑ   | $V_{DS} = 80 \text{ V}, V_{GS} = 0$                               |
| Gate to source cutoff voltage              | $V_{\rm GS(off)}$   | 1.0 | _    | 2.0  | V    | $I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$                     |
| Static drain to source on state resistance | $R_{DS(on)}$        | _   | 0.2  | 0.25 | Ω    | $I_D = 2.5 A$<br>$V_{GS} = 10 V^{*1}$                             |
|  |                     | _   | 0.25 | 0.35 | Ω    | $I_D = 2.5 \text{ A}$ $V_{GS} = 4 \text{ V}^{*1}$                 |
| Forward transfer admittance                | $ y_{fs} $          | 3   | 5    | _    | S    | $I_D = 2.5 A$<br>$V_{DS} = 10 V^{*1}$                             |
| Input capacitance                          | Ciss                | _   | 525  | _    | pF   | $V_{DS} = 10 \text{ V}$   |
| Output capacitance                         | Coss                | _   | 205  | _    | pF   | $V_{GS} = 0$  |
| Reverse transfer capacitance               | Crss                | _   | 60   | _    | pF   | f = 1 MHz   |
| Turn-on delay time                         | $t_{\text{d(on)}}$  | _   | 5    | _    | ns   | $I_{D} = 2.5 \text{ A}$   |
| Rise time                                  | t <sub>r</sub>      | _   | 30   | _    | ns   | V <sub>GS</sub> = 10 V  |
| Turn-off delay time                        | t <sub>d(off)</sub> | _   | 180  | _    | ns   | $R_L = 12 \Omega$   |
| Fall time                                  | t <sub>f</sub>      | _   | 65   | _    | ns   |   |
| Body to drain diode forward voltage        | $V_{DF}$            | _   | 1.0  | _    | V    | $I_F = 5 \text{ A}, V_{GS} = 0$                                   |
| Body to drain diode reverse recovery time  | t <sub>rr</sub>     | _   | 170  | _    | μs   | $I_F = 5 \text{ A}, V_{GS} = 0,$<br>$dIF/dt = 50 \text{ A}/\mu s$ |

Note: 1. Pulse Test

See characteristic curves of 2SK1300



0.05

0.1 0.2 0.5 1

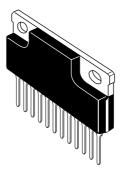
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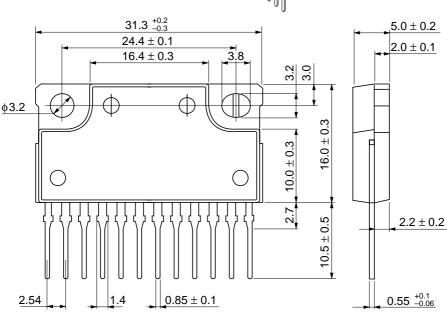
Drain to Source Voltage V<sub>DS</sub> (V)

5 10 20

50 100

Unit: mm





|   |   |   |   |   |   |   |   |   |   |    |    | 1     |
|---|---|---|---|---|---|---|---|---|---|----|----|-------|
| ς |   |   | ш |   |   |   |   |   |   |    |    | , III |
| ١ | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12/   |
|   |   |   |   |   |   |   |   |   |   |    |    |       |

| Hitachi Code             | SP-12TA |
|--------------------------|---------|
| JEDEC                    | I       |
| EIAJ                     |         |
| Weight (reference value) | 6.1 g   |

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